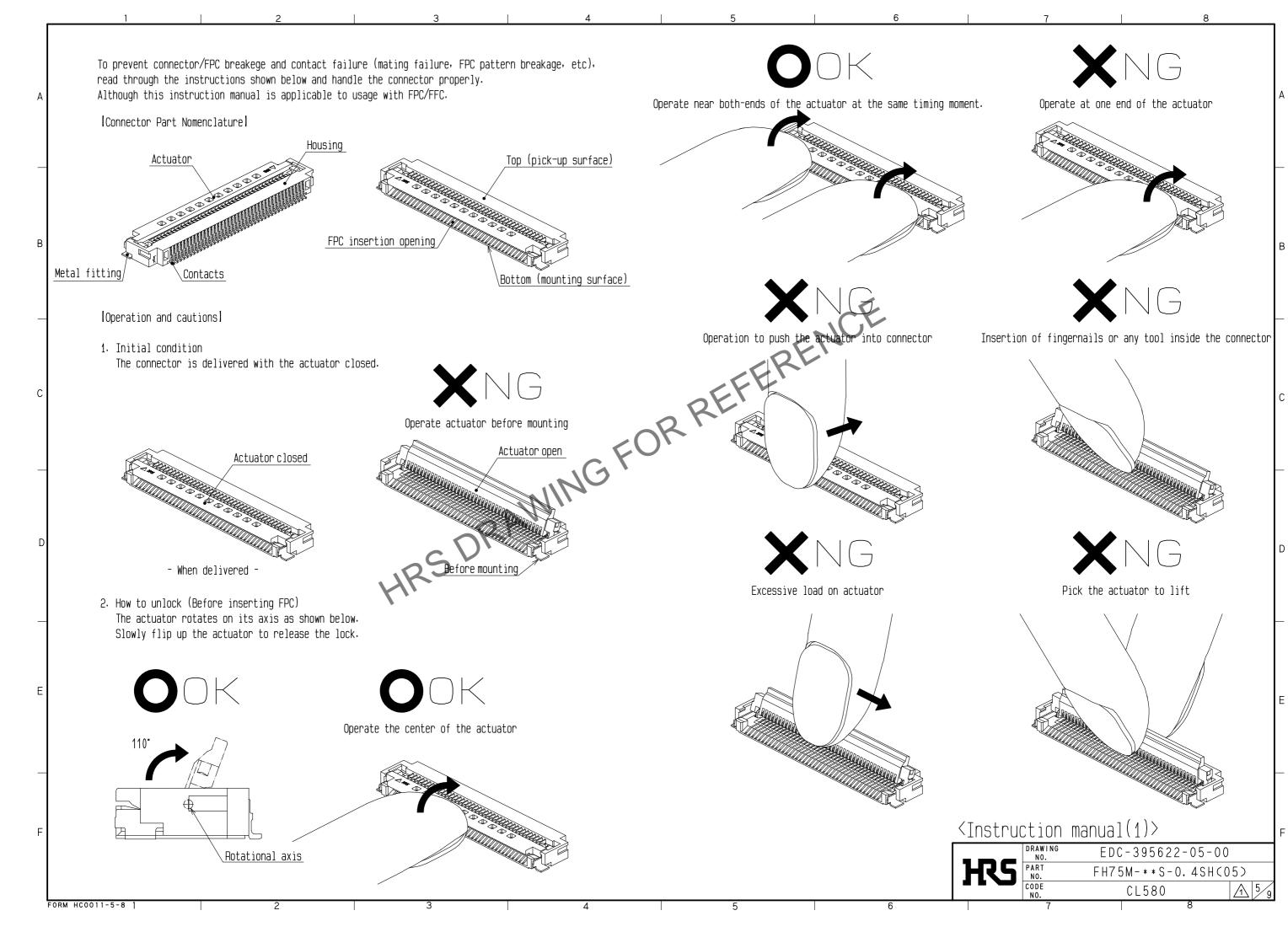
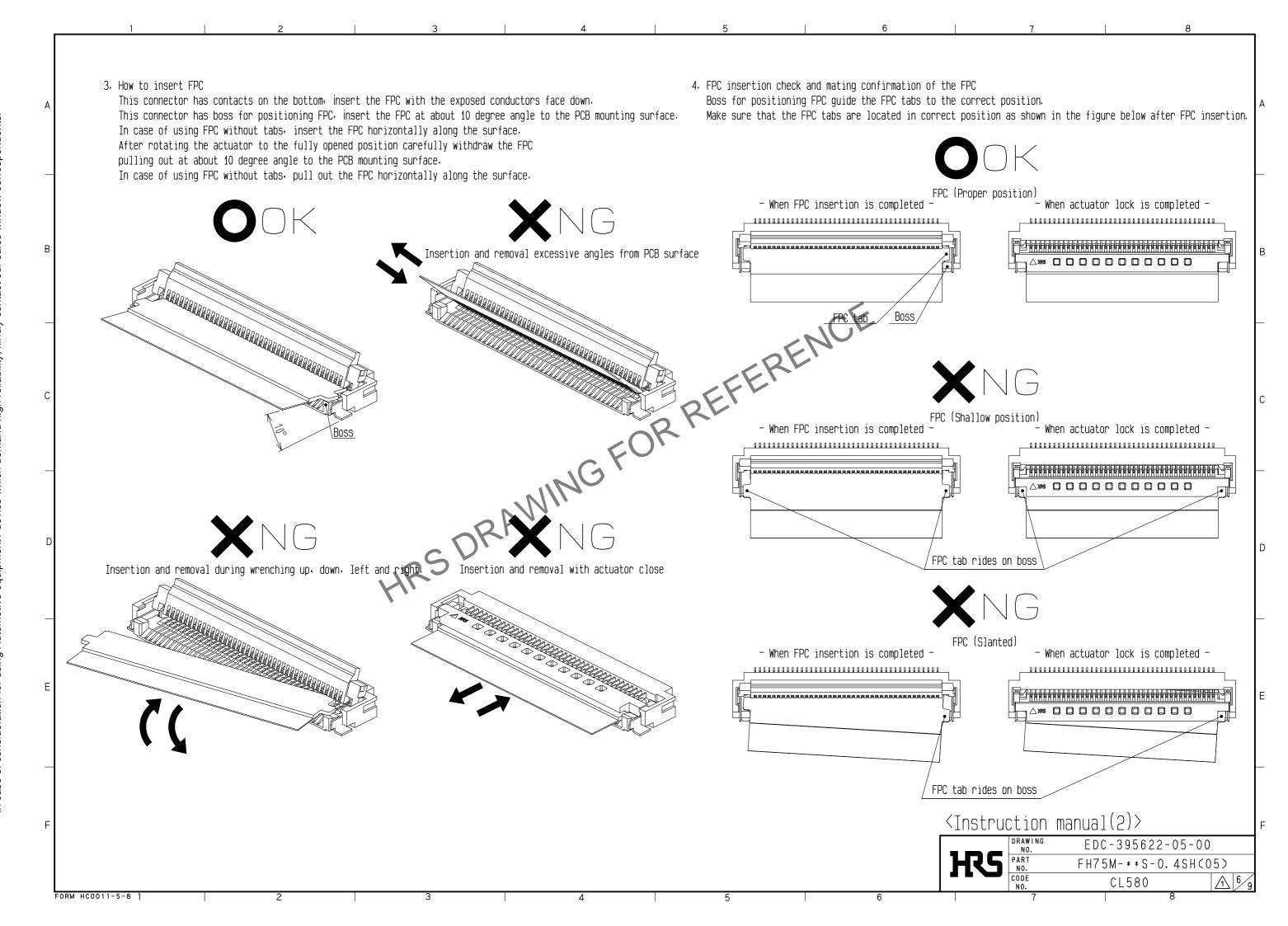


	Code Number	Number	Number Dimension of connector, PCB mounting pattern, stencil pattern and FPC Dimension of drawing for packing													
Part No.		of		B B	C C	D moun	E E	F F	G		 		i i		Packing	Q
FH75M-80S-0.4SH(05)		contacts 80	A 36.2	21.6	22.47	24.45	26.2	24.0	240	32.4	26.2	56	52.4	M 27.6	E7 4	61.4
FH75M-100S-0.4SH(05)		100	44.2	31.6 39.6	40.47	42.45	44.2	42.0	42.0	40.4	34.2	72	68.4	37.6 45.6	73.4	61.4 77.4
FH75M-120S-0.4SH(05)		120	52.2	47.6	40.47	50.45	52.2	50.0	50.0	18.4	34.2	72	68.4	53.5	73.4	77.4
FH75M-100S-0.4SH(05) FH75M-120S-0.4SH(05) TH75M-120S-0.4SH(05) TH75M-120S-0.4SH(05)	e number are c r detailed inf	urrent	tly uni	der pl	or anning oduct	g. varia	tion.	RE								

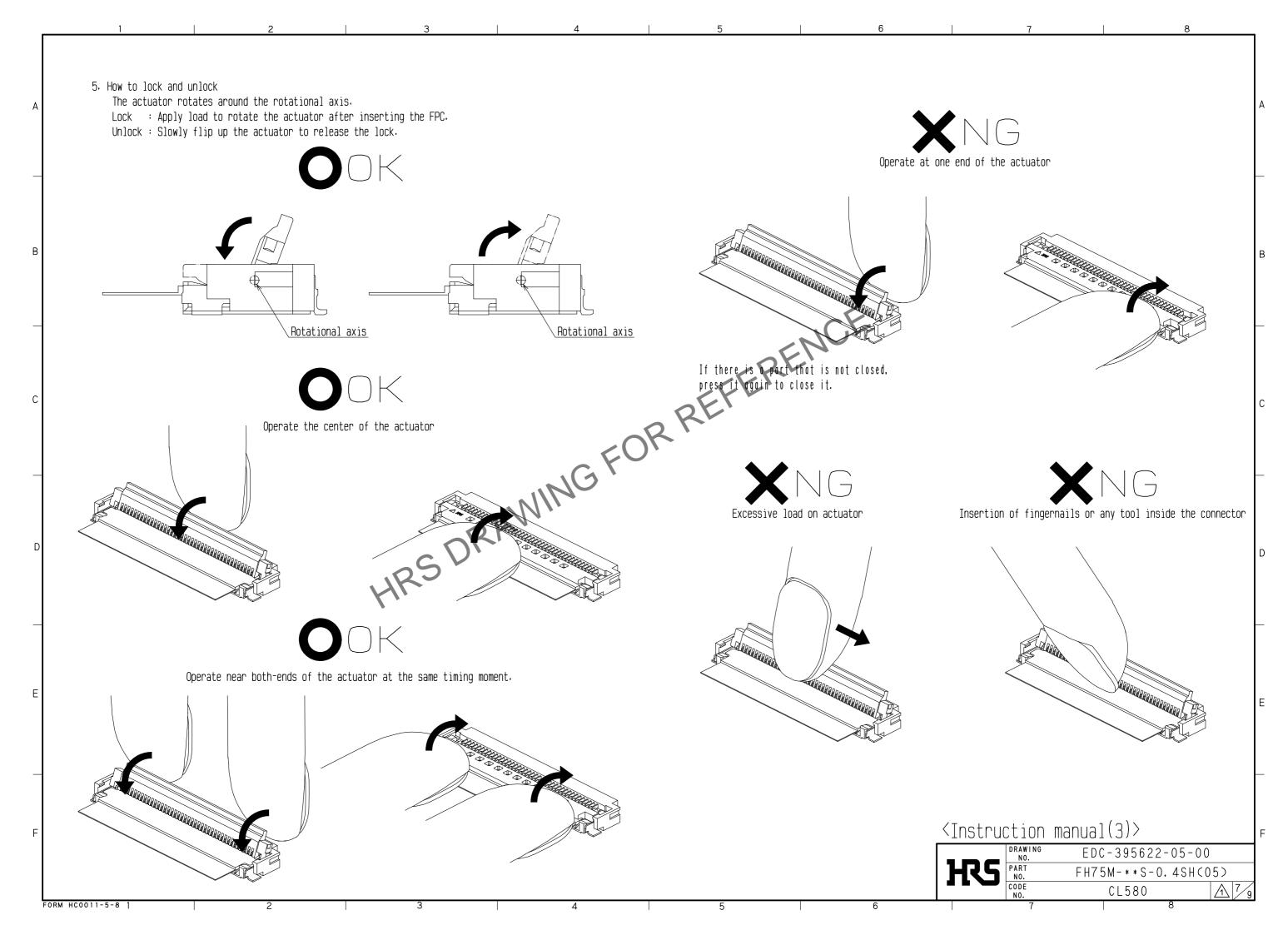
PART NO.
CODE NO. EDC-395622-05-00 FH75M-**S-0.4SH(05) 1 4 9 CL580

FORM HC0011-5-8 1 4









| Instructions for PCB layout

Please design a PCB layout not to apply load to connector and FPC.

[Cautions]

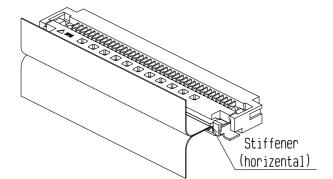
- When fixing FPC after FPC cabling, avoid pulling FPC, and route the wire FPC with slack. In this regard, the stiffener is parallel to the PCB.
- Do not mount other components touching to the FPC underneath the FPC stiffener.
- Make adjustments with the FPC manufacturer for FPC bending performance and wire breakage.
- Keep spaces for the actuator movement and its operation for PCB design and component layout.
- Please contact Hirose incase you would like to use an FPC with a different dimension or shape than recommended.

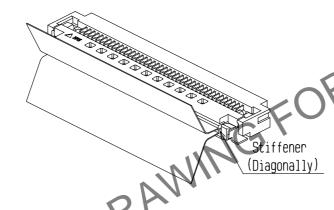


No load applied to stiffener



Load applied to stiffener

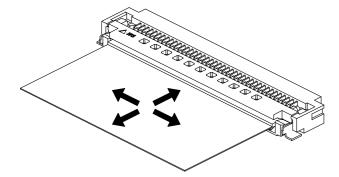


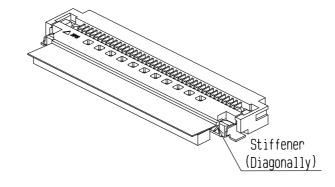




Load applied to FPC







Instructions for mounting on the PCB

- Refer to recommended layouts for PCB, stencil pattern and FPC dimension.
- When there is silk printing etc. on the bottom of the connector, please check the mounting condition before use.
- Apply reflow temperature profile within the specified conditions.

 The mounting condition may change depending on the type of cream solder, manufacturer, PCB size.

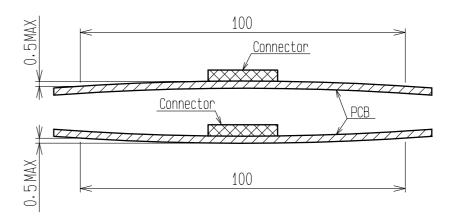
 Please check the mounting condition before use and conditions of other mounting parts.
- Prevent warpage of PCB, the co-planarity of the connector is less than 0.1mm. but when the warpage of the PCB is large, soldering failure occurs.
- When mounting on the flexible board, please make sure to put a stiffener on the backside of the flexible board.
- We recommend a glass epoxy material with the thickness of 0.3 mm min.
- Do not add 0.5 N or greater external force when unreel or adsorb the connector etc. or it may get broken.

| Instructions for PCB handling after mounting the connector

Due to warpage of the PCB, load may be applied to the connector and it may be damaged.

- ·Splitting a large PCB into several pieces
- ·Screwing the PCB
- During the handling described above, do not exert an excessive force on the PCB.
- Otherwise, the connector may become defective.
- -The warp of a 100 mm wide PCB should be 0.5 mm or less.

The warp of PCB suffers stress on connector and the connector may become defective



[Instructions of hand soldering]

- Do not perform hand soldering with the FPC inserted into the connector.
- Do not apply excessive heat. And soldering iron must not touch connector except terminal leads area.
- Do not supply excessive solder (flux).

<Instruction manual(4)>

HRS | DRAWING | EDC-395622-05-00 | PART | NO. | FH75M-**S-0.4SH(05) | CL580 | A | 8 |

FORM HC0011-5-8 1 2 3 4 5

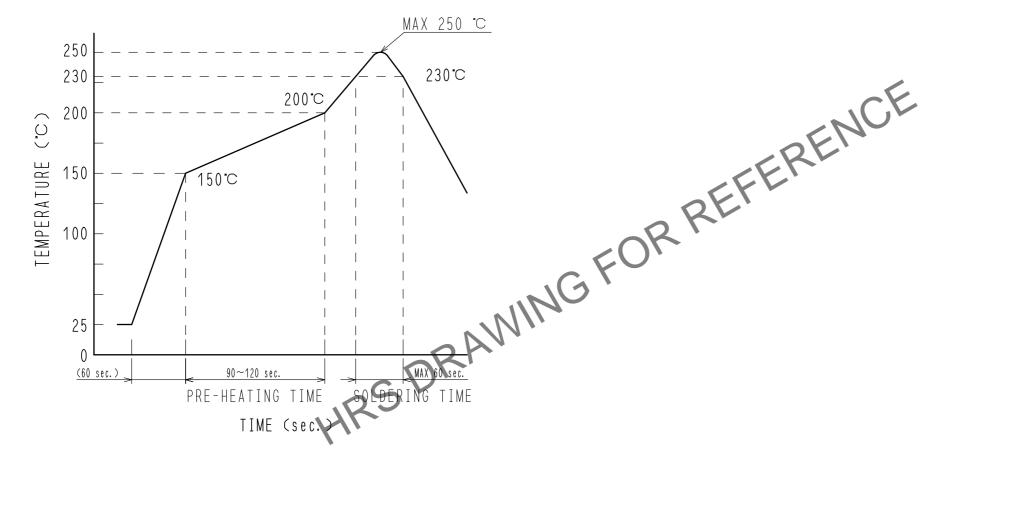
Recommended reflow temperature profile

The temperatures mentioned above refer to the PCB surface temperature near the connector leads. In individual applications the actual temperature may vary, depending on solder paste type volume/thickness and board size/thickness.

Consult your solder paste and equipment manufacturer for specific recommendations.

-Reflow method:IR reflow

-Number of reflow cycles:2 cycles MAX.



жs	DRAWING NO.	EDC-395622-05-00		
	PART NO.	FH75M-**S-0.4SH(0	5)	
	CODE NO.	ClCode	<u></u>	9/9

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